

# Gas Plasma Reactors

Compact, Barrel Type, Low Temperature Ashing Device

## PR500/510

High-frequency output

500W

Reaction chamber

ø215 x 305mm

Designed with large chamber size made of quartz considered almost completely resistant against most plasma processes



PR500 (Manual version)



PR510 (Touch panel version)

### ■ Features

- Compact, space saving design with oscillation section integrated with a portion of the chamber
- Outstanding operability and safety with the automatic tuning system as standard component
- Equipped with a large quartz chamber (ø215mm) which can process big testing samples

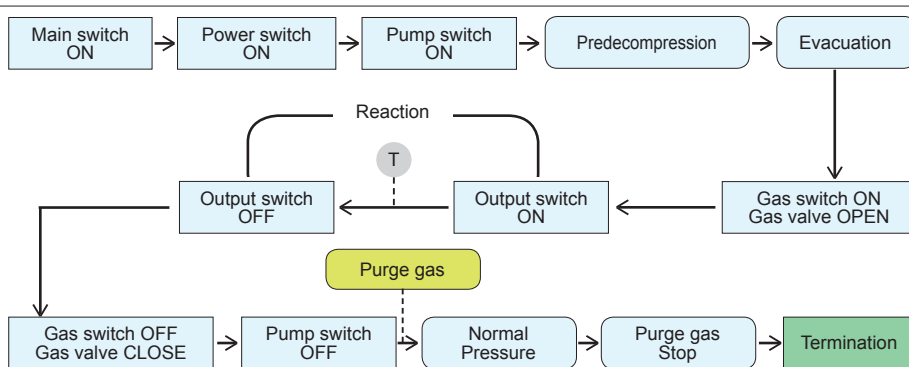
### ■ Applications

- Removal of photoresist
- Cleaning of parts
- Surfactant treatment
- Micro polishing
- Corresponds to wafer and glass substrate

### ■ Specifications

Model	PR500 (Flow meter)	PR510 (Mass flow meter)
Method	Barrel type chamber direct plasma	
High frequency output	Max. 500W	
Oscillating frequency	13.56MHz	
Tuning method	Automatic tuning	
Reaction chamber	Made of quartz, ø215×305mm	
Reaction gas	Dual system (O <sub>2</sub> / CF <sub>4</sub> )	
Control system	Manual	Automatic touch panel
Piping material	Stainless steel, Teflon	
External dimensions (W×D×Hmm)	438×520×760	520×630×760
Weight	~60kg	~60kg
Power source (50/60Hz)	AC115V / AC220V	
Standard accessories	Connection cable: 1 complete set Vacuum grease: 1 pc. O-ring for reaction chamber: 1pc.	
Optional accessories	Frame for wafers (2, 3, 4, 5, 6 inches) Multi-purpose angled frame Aluminum etching tunnel Stand	

## Operation Flowchart



## Control Panel



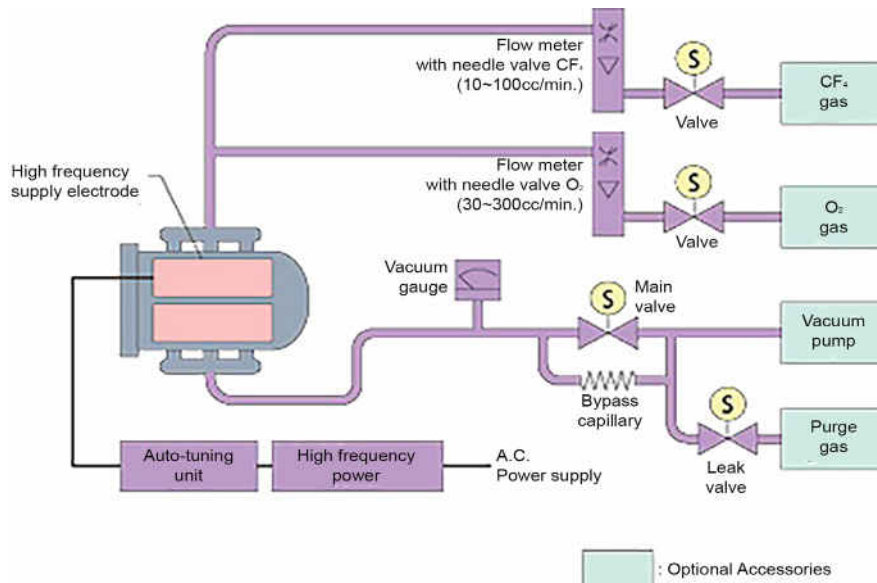
PR500

## Chamber



ø215mm large caliber chamber

## Piping System (PR500/510)



## Wafer Ashing



The gas plasma equipment has a wide range of applications from ashing, etching, dry cleaning, etc.